

Features

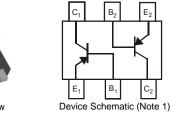
- **Epitaxial Die Construction**
- Complementary PNP Type Available (BC847BV)
- Ultra-Small Surface Mount Package
- Lead Free By Design/RoHS Compliant (Note 3)
- "Green" Device (Notes 5 and 6)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound, Note 6. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D

E.

- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.003 grams (approximate)



Bottom View Top View Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	lc	-100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	PD	150	mW
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ heta JA}$	833	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 4)	V _{(BR)CBO}	-50	_		V	$I_{\rm C} = 10 \mu A, I_{\rm B} = 0$
Collector-Emitter Breakdown Voltage (Note 4)	V _{(BR)CEO}	-45	_	_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage (Note 4)	V _{(BR)EBO}	-5	—	_	V	$I_{E} = 1 \mu A, I_{C} = 0$
DC Current Gain (Note 4)	h _{FE}	220	290	475		$V_{CE} = -5.0V, I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage (Note 4)	V _{CE(SAT)}	—		-100 -400	mV	$I_{C} = -10mA$, $I_{B} = -0.5mA$ $I_{C} = -100mA$, $I_{B} = -5.0mA$
Base-Emitter Saturation Voltage (Note 4)	V _{BE(SAT)}	-	-700 -900	-	mV	I _C = -10mA, I _B = -0.5mA I _C = -100mA, I _B = -5.0mA
Base-Emitter Voltage (Note 4)	V _{BE(ON)}	-600 —		-750 -820	mV	V _{CE} = -5.0V, I _C = -2.0mA V _{CE} = -5.0V, I _C = -10mA
Collector-Cutoff Current (Note 4)	I _{CBO}	—		-15 -4.0	nΑ μΑ	V _{CB} = -30V V _{CB} = -30V, T _A = 150°C
Gain Bandwidth Product	f _T	100	_	_	MHz	V _{CE} = -5.0V, I _C = -10mA, f = 100MHz
Output Capacitance	C _{OB}		_	4.5	pF	V _{CB} = -10V, f = 1.0MHz
Noise Figure	NF	_	_	10	dB	I_{C} = -0.2mA, V _{CE} = -5.0Vdc, R _S = 2.0KΩ, f = 1.0KHz, BW = 200Hz

1. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways). Notes:

2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

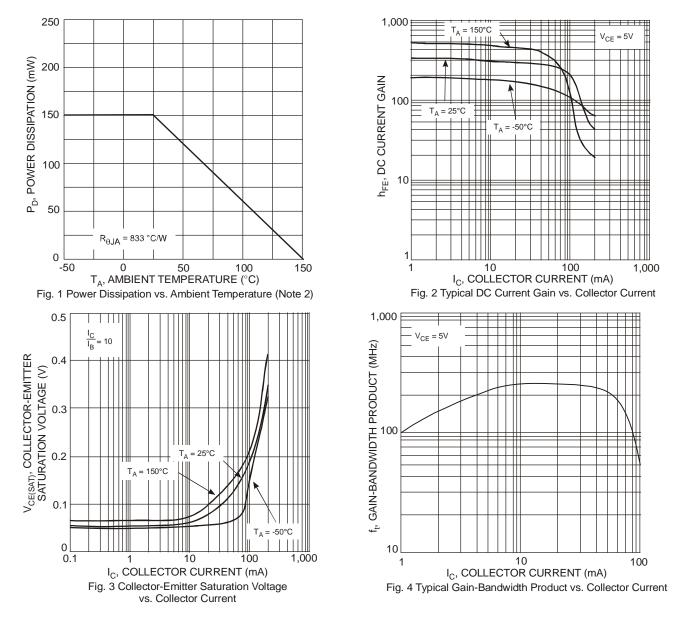
3. No purposefully added lead.

4. Short duration pulse test used to minimize self-heating effect.

- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 6. UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



BC857BV



Ordering Information (Note 7)

Part Number	Case	Packaging
BC857BV-7	SOT-563	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

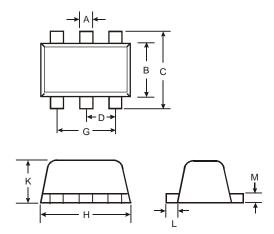
Marking Information

Date Code Key				К5 Ц	SV YM	YM : Y =	= Date C Year (ex	ode M : T = 20					
Year	2003	2004	2005	2006	2007	2008	2009	201	0 201	1 2012	2013	2014	2015
Code	Р	R	S	Т	U	V	W	Х	Y	Z	А	В	С
Month	Jan	Feb	Mar	Apr	Ма	ıy Ju	In	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	6	7	8	9	0	Ν	D



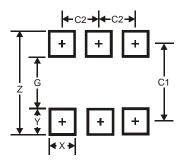
BC857BV

Package Outline Dimensions



SOT-563						
Dim	Min	Max	Тур			
Α	0.15	0.30	0.20			
В	1.10	1.25	1.20			
С	1.55	1.70	1.60			
D	-	-	0.50			
G	0.90	1.10	1.00			
Н	1.50	1.70	1.60			
κ	0.55	0.60	0.60			
L	0.10	0.30	0.20			
Μ	0.10	0.18	0.11			
All	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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